

2811  
PATENT

Case Docket No. MICRON.172A

Date: February 5, 2003

Page 1

In re application of : Derraa et al.  
App. No. : 09/945,065  
Filed : August 30, 2001  
For : METAL SILICIDE  
ADHESION LAYER FOR  
CONTACT STRUCTURES  
Examiner : Junghwa M. Im  
Art Unit : 2811

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February 6, 2003

(Date)

Linda H. Liu, Reg. No. 51,240

UNITED STATES PATENT AND TRADEMARK OFFICE  
P.O. Box 2327  
Arlington, VA 22202

Sir:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated as shown below:

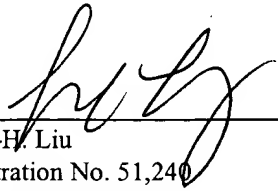
## CLAIMS AS FILED

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA	RATE	ADDITIONAL FEE
Total Claims	19	35	= 0 ×	\$18	= \$0
Independent Claims	2	3	= 0 ×	\$84	= \$0
If application has been amended to contain multiple dependent claim(s), then add				\$280	= \$0
Time Extension Fee					\$0
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0

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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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3/13/3  
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Applicant : Derraa et al. ) Group Art Unit 2811  
Appl. No. : 09/945,065 )  
Filed : August 30, 2001 )  
For : METAL SILICIDE ADHESION )  
LAYER FOR CONTACT )  
STRUCTURES )  
Examiner : Junghwa M. Im

AMENDMENT

United States Patent and Trademark Office  
P.O. Box 2327  
Arlington, VA 22202

Dear Sir:

In response to the Office Action mailed November 6, 2002, please amend the above-identified application as indicated below:

IN THE CLAIMS:

Please cancel Claim 5 without prejudice.

Please amend the claims as follows:

1. (Amended) An integrated circuit comprising:

a silicon substrate;

B<sup>1</sup> an insulating layer formed on the silicon substrate wherein the insulating layer has an opening that extends from an upper surface of the insulating layer to an upper surface of the substrate so as to expose the upper surface of the substrate;

a metal layer formed in the opening wherein a first portion of the metal layer is formed on the exposed upper surface of the substrate and reacts with silicon in the substrate to form metal

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